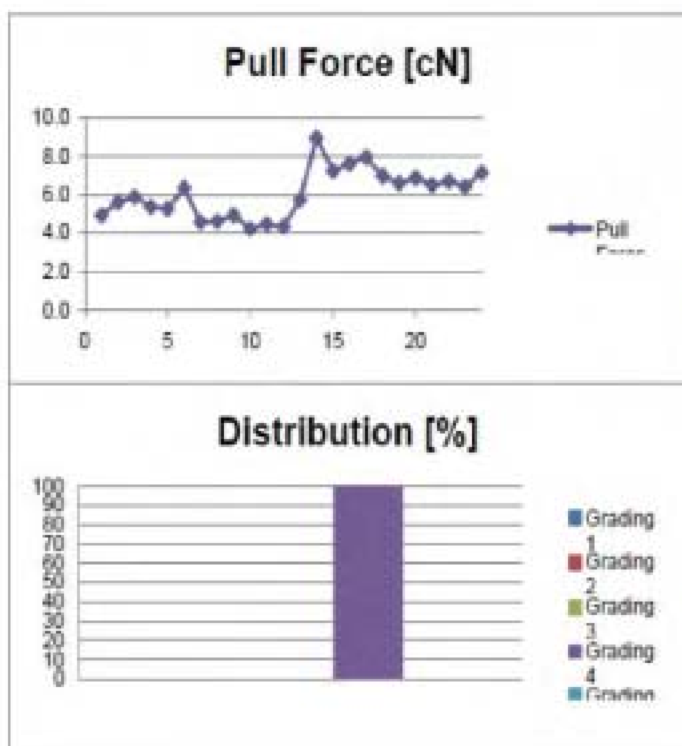
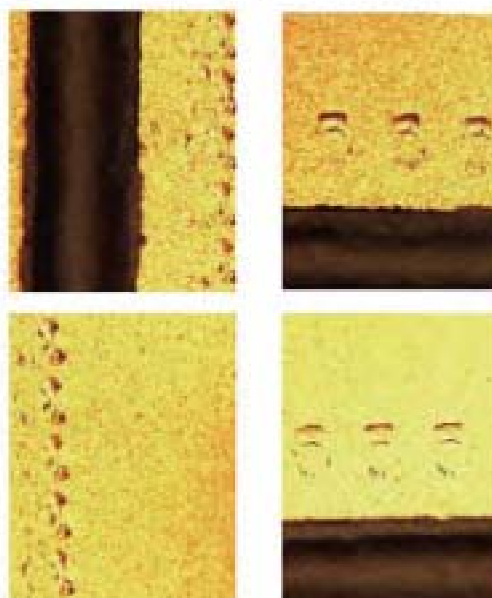
VERTECH 上鼎電子

ⓘ Ni 150 u" + Gold 12 u"

Bondability Analysis

Statistics			Explanations Grading	
	PF [cN]	Distribution [%]	GOLD	ALUMINIUM
Average	6.05	0 Grading 1	Ball lift off	1st wedge lift off
Stdev	1.26	0 Grading 2	Break at neck	Break at 1st wedge
Min	4.2	0 Grading 3	Break at wire	Break at wire
Max	8.9	100 Grading 4	Break at wedge	Break at 2nd wedge
Range	4.7	0 Grading 5	Wedge lift off	2nd wedge lift off





Sample No. As delivered

#	Pull Force	Pull Grading
1	4.9	4
2	5.6	4
3	5.9	4
4	5.4	4
5	5.3	4
6	6.3	4
7	4.6	4
8	4.6	4
9	4.9	4
10	4.2	4
11	4.5	4
12	4.4	4
13	5.7	4
14	8.9	4
15	7.2	4
16	7.6	4
17	8.0	4
18	7.0	4
19	6.6	4
20	6.9	4
21	6.5	4
22	6.7	4
23	6.4	4
24	7.1	4

Vertech

is excellent in bondability of Wire Bonding (based on immersion Ni 150 u" + Gold 12 u")! This sample board is highly approved by our customer.
Please refer to our statistic result and pull force result above.

The solution to your PCB needs
Where efficiency brings satisfaction!